



Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **SR-0403-01 REV.01** DATE: 11/8/2004

Product Affected: TSOP32 (PH32) package
(see attachment for affected part #s)

Date Effective: 6/5/2004

MEANS OF DISTINGUISHING CHANGED DEVICES:

- ☐ Product Mark
☒ Back Mark Assembly lot number will have an "A" prefix.
☐ Date Code
☐ Other

Contact: Geoffrey Cortes

Title: Corporate QA / Reliability Manager

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Attachment:: ☒ Yes ☐ No

Samples: See attachment

DESCRIPTION AND PURPOSE OF CHANGE:

- ☐ Die Technology
☐ Wafer Fabrication Process
☐ Assembly Process
☐ Equipment
☐ Material
☐ Testing
☒ Manufacturing Site
☐ Data Sheet
☐ Other

REV.01 - The purpose of this PCN is to revise the affected package types and products listed in the original PCN (SR-0403-01). Package types PZ28 and PH44 (except - 71V016SAxxPH) have been removed from the affected package types and products list from OSE-T. The assembly of PH32 and PH44 (71V016SAxxPH) will still remain in OSE-T

The PCN effective date will be the same as the original PCN.

OSE-T is a qualified assembly facility for TSOP package family. IDT is adding an additional package type TSOP32 (PH32) to this facility.

RELIABILITY/QUALIFICATION SUMMARY:

Please see attachment for reliability/qualification data.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____

☐ *Approval for shipments prior to effective date.*

Name/Date: _____

E-Mail Address: _____

Title: _____

Phone# /Fax# : _____

CUSTOMER COMMENTS:

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____



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ATTACHMENT - PCN #: SR-0403-01 REV.01

PCN Type: To qualify an alternate assembly facility.

Data Sheet Change: There is no change in Moisture Sensitive Level (MSL).

Detail of Change: The purpose of this PCN is to revise the affected package types and products list. Package types PZ28 and PH44 (except - 71V016SAxxPH) have been removed from the affected package types and products list from OSE-T.

The PCN effective date will be the same as the original PCN.

OSE-T is a qualified assembly facility for TSOP package family. IDT is adding an additional package type TSOP32 (PH32) to this facility. There is no change in existing process or assembly material set and Moisture Sensitive Level (MSL). Products will be shipped at the existing MSL and each shipment is labeled with the correct MSL. Please refer to the label on each shipment for MSL information.

The affected products are as follow:

IDT71V016SA10PH	IDT71V016SA20PH	IDT71V124SA15PH
IDT71V016SA10PHI	IDT71V016SA20PHI	IDT71V124SA15PHI
IDT71V016SA12PH	IDT71V124SA10PH	IDT71V124SA20PH
IDT71V016SA12PHI	IDT71V124SA10PHI	IDT71V124SA20PHI
IDT71V016SA15PH	IDT71V124SA12PH	
IDT71V016SA15PHI	IDT71V124SA12PHI	

Note: T & R (shipping method) "8" is added to the part number and for industrial grade, letter "I" is added to the part number.

Samples are not built ahead of the change and are limited to selective devices. Please contact your local field sales representative for sample availability and additional information.



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PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT - PCN #: SR-0403-01 REV.01

Qualification Plan: P03-07-02

Test Vehicle: IDT71V124

Qualification Test Plan and Results:

Test Description	Test Method	Sample Size /# of Fails	Test Results
*Highly Accelerated Stress Test (HAST) (100 Hrs, @ 130°C/85%RH,Static Bias)	JESD22-A110-B	45/0	43/0 (a)
*Temperature Cycling (-65°C to +150°C, 500 cycle)	JESD22-A104-B	45/0	45/0
*Auto Clave (SPP) (168Hrs, @ 2ATM, 121°C)	JESD22-A102-C	45/0	44/0 (b)
Physical Dimensions	JESD22-B100-B	5/0	5/0
Resistance to Solvents	MIL-STD-883, M 2015	3/0	3/0
Solderability	JESD22-B102-C J-STD-002	3/0	3/0
Bake & Ball Shear Test	JESD22-B116	5/0	5/0
Bond Pull Test	MIL-STD-883, M 2011	5/0	5/0
X-ray Examination	MIL-STD-883, M 2015	45/0	45/0
Adhesion of Lead Finish	MIL-STD-883, M 2025	3/0	3/0
Lead Integrity Test	JESD22-B105C	3/0	3/0
External Visual Inspection	JESD22-B101	25/0	25/0
Internal Visual Inspection	MIL-STD-883, M 2010	5/0	5/0
Moisture Sensitive Level	J-STD-020B	90/0	90/0

Notes: * Test requires moisture pre-conditioning sequence per JESD22-A113C.

(a) Missing units.

(b) Mechanical reject.